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A both gaussian and sinusoidal phase-to-amplitude converter for low-power ultra-high-speed Direct Digital Synthesizers

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Abstract—This paper introduces a new bipolar differential pair topology for both gaussian and sinusoidal signal shaping, to be used as a phase-to-amplitude converter alternative in low-power ultra-high-speed DDS. A DDS using this converter, with a 9-bit frequency resolution and an 8-bit amplitude resolution has been designed in a 0.13 μ m SiGe BiCMOS technology, with $f_t/f_{\max}$ of 200/250 GHz, and simulated up to a 20 GHz operating clock frequency. It consumes 585 mW under a 2.8 V power supply. Simulated triangle shape allows an optimal SFDR of -44.5 dBc in sinus mode and a SLRR of -43.5 dBc in gaussian mode.

I. INTRODUCTION

Direct digital synthesis is a technique which allows generation of arbitrary waveforms from a fixed frequency reference. Traditional DDS architecture [1] is made up of three main blocks as depicted on fig. 1. The DDS first accumulates a programmed phase increment $\Delta\phi$ through a Phase Accumulator (PA) to make a digital phase ramp used to address a memory (generally a ROM) which contains the digital samples of the signal to be generated: it acts as a Phase-to-Amplitude Converter (PAC). Near the end, the digitally formatted signal is converted to analog by a linear Digital-to-Analog Converter (DAC). The main characteristics of the DDS are: fast-settling time of about one clock period, frequency resolution directly related to the phase accumulator resolution, and wideband behavior with digital modulation capabilities [2]. All these advantages make the DDS an interesting candidate for modern microwave applications. However, ROM are known to consume a large amount of area and power, which are prohibitive for embedded systems. To overcome this, a trade-off on the diversity of waveforms that can be generated had to be made in order to suppress the ROM. Thus, high-speed DDS are focused on sine wave generation [3], [4], [5] and are then able to reach only a few hundred mW on low-cost Silicon-Germanium technologies [6], [7].

Our work intends to regain a part of the "arbitrary waveform generator" aspect of DDS by proposing a reconfigurable PAC which, when coupled to a DDS, is able to generate either sinusoidal or gaussian shaped waves. Such DDS could then be used in UWB transceivers since IR-UWB emitters use

gaussian shaped pulses, while traditional receivers use sinus signals through mixers for frequency up and down conversion.

II. ROM-LESS DDS ARCHITECTURE

Fig. 1: Typical DDS architecture

Fig. 2: ROM-less DDS architecture

It has already been shown that the hyperbolic tangent characteristic of bipolar transistors pairs is suitable to approximate either sine wave [8] or gaussian shaped [9] functions. A DDS architecture based on such a behavior has previously been reported [10]. This architecture, shown fig. 2, and compared to the classical one on fig. 1 uses a $n - 1$ -bit inverter between the PA and the DAC, while the PAC has been moved from the digital to the analog part after the DAC. The added inverter, driven by the MSB of the PA, transforms the digital PA's ramp to a digital triangular signal. This digital triangular signal is analog converted by the DAC, and then shaped by the analog PAC in order to fit the requested signal (in this case only a sine wave). This ROM-less architecture and its analog shaping technique have the advantage to decrease the circuit

complexity and hence to save power consumption. The PAC presented in this paper cumulates the possibility to generate both a gaussian shape and a sine wave through a simple reconfiguration technique. A DDS with a 9-bit pipeline PA, a 2×4 -bit plus 1-bit accumulator scheme, a 8-bit current-steering linear DAC, and this new PAC has then been designed in a 3-stage Emitter-Coupled-Logic.

III. PHASE-TO-AMPLITUDE CONVERTER

The Gaussian/Sinus Phase-to-Amplitude Converter (G/S-PAC) proposed on fig. 3 is made up of two differential pairs of bipolar transistors (Q_1, Q_2) and (Q_3, Q_4), both biased at the same current (I_p) and with the same voltage reference (V_a).

Fig. 3: Schematic of the G/S-PAC

The G/S-PAC is driven in large-signal conditions with a differential triangular signal ($V_i^+ - V_i^-$) generated by the DDS. The circuit is biased and routed in such a way that a positive (negative) gaussian pulse is generated at G/S-PAC output for the positive (negative) part of the triangular input signal (fig. 4).

Fig. 4: Principle of the triangle-to-gaussian conversion

According to Kirchhoff law, the left branch current I_l of the G/S-PAC circuit is

$$I_l = I_{C1} + I_{C3} \quad (1)$$

As a first approximation, we can assume Ebers-Moll model for bipolar transistors. With a forward gain $\alpha_F = 1$, equation (1) becomes

$$I_l = \frac{I_p}{2} \left[2 + \tanh\left(\frac{V_i^+ - V_a}{2U_T}\right) + \tanh\left(\frac{V_a - V_i^-}{2U_T}\right) \right] \quad (2)$$

In the same way, the right branch current I_r is

$$I_r = \frac{I_p}{2} \left[2 - \tanh\left(\frac{V_i^+ - V_a}{2U_T}\right) - \tanh\left(\frac{V_a - V_i^-}{2U_T}\right) \right] \quad (3)$$

Considering the differential output voltage V_o as the product between load resistor R and the differential current $I = I_l - I_r$, equations (2) and (3) give the sum of input/output relationships in large signal condition for differential amplifiers following hyperbolic tangent law

$$V_o = RI_p \left[\tanh\left(\frac{V_i^+ - V_a}{2U_T}\right) + \tanh\left(\frac{V_a - V_i^-}{2U_T}\right) \right] \quad (4)$$

Introducing variables

- $V_i = V_i^+ - V_i^-$ as differential mode input voltage,
- $V_c = (V_i^+ + V_i^-)/2$ as common mode input voltage,
- $a = 2(V_a - V_c)$,

and re-injecting these in equation (4) leads to the direct relation between differential output voltage V_o , input differential voltage V_i and the introduced parameter a

$$V_o = RI_p \left[\tanh\left(\frac{V_i - a}{4U_T}\right) + \tanh\left(\frac{V_i + a}{4U_T}\right) \right] \quad (5)$$

Fig. 5: Normalized input/output G/S-PAC's transfer characteristic.

Equation (5) and each of its tanh components showing two distinct saturation levels are plotted fig. 5. The proposed structure uses the "a" parameter to shift both tanh characteristics by $\pm a$ along the horizontal $V_i/(4U_T)$ axis. Thus, with "a" properly chosen, a positive differential input voltage sets up (Q_3, Q_4) in *positive* saturation while (Q_1, Q_2) pair imposes its tanh behavior. Likewise, a negative input voltage sets up (Q_1, Q_2) in *negative* saturation while (Q_3, Q_4) pair imposes its tanh behavior. Thereby, by applying a differential triangular input voltage, the positive (or negative) side gives a good

approximation of a gaussian pulse by hyperbolic tangent. Moreover, if "a" is chosen equal to zero, V_o can be rewritten as

$$V_o = 2RI_p \tanh\left(\frac{V_i}{4U_T}\right) \quad (6)$$

Thus, $a = 0$ (i.e. $V_a = V_c$) leads to a pure tanh behavior for the G/S-PAC. With amplitude of V_i properly chosen, the differential triangular input voltage is curved, following tanh law, to approximate a sine wave.

IV. SIMULATIONS AND RESULTS

In order to properly set up the amplitude of the triangular input voltage applied by the DDS to the G/S-PAC, an *ideal* triangular signal generator has been used to drive the G/S-PAC in optimization simulations. The well-known bell shaped frequency spectrum of generated gaussian pulses is plotted fig. 6 for various amplitude of G/S-PAC input voltage.

Fig. 6: Frequency spectrum of gaussian shaped pulses for various peak amplitudes from an ideal generator.

Fig. 7: Sinus' harmonics and resulting SFDR versus peak amplitude of input voltage from an ideal generator.

The tanh approximation introduces side-lobes that can be minimized to a Side Lobes Rejection Ratio (SLRR) of -43.5 dBc for an input peak amplitude voltage of 565 mV obtained with $V_c = 1.59$ V and $V_a = 1.77$ V. The same optimisation is made for the sinus-mode. The third and the fifth harmonics of the generated sinus are plotted fig. 7 versus the

triangle amplitude. An optimal Spurious Free Dynamic Range (SFDR) of -44.5 dBc can be reached for a peak amplitude voltage of 220 mV obtained with $V_c = V_a = 1.79$ V.

Fig. 8: Transient simulation for gaussian-mode G/S-PAC driven by a DDS with phase increment of 1 and $F_{clk} = 20$ GHz

Fig. 9: Transient simulation for sinus-mode G/S-PAC driven by a DDS with phase increment of 1 and $F_{clk} = 20$ GHz

The G/S-PAC proposed in this paper has been used to design a first version of a 9-bit ROM-less DDS in the IBM $0.13\mu\text{m}$ BiCMOS SiGe process. This technology provides high-performance HBT with f_t/f_{max} of $200/250$ GHz. Obviously, our G/S-PAC require a calibration phase. In order to reach optimal performances in future measurements, the DAC of the DDS architecture has been designed with a voltage controlled output amplitude. Since SFDR and SLRR depend on DAC linearity and matching of components, the analog part of the circuit's layout has been focused on these two main constraints.

The full circuit has been simulated with BSIM4 model for MOS transistors and VBIC model for HBT with process parameters filled from the BiCMOS8HP design kit to Spectre simulator under Cadence 5.1.41. The DDS has been simulated at a maximum operating clock frequency of 20 GHz and consumes only 585 mW (209 mA under 2.8 V). Such a consumption should be considered low for DDS and can be compared to those of others in tab. I, in which our DDS exhibit a high FOM. Further optimizations should improve this consumption.

TABLE I: Comparison of differents ultra high-speed DDS

Ref.	Technology process	f_i NPN (GHz)	Clock freq. (MHz)	Acc. size (bit)	Accumulator decomposition	Power (mW)	Die area (mm ²)	FOM $\frac{\text{MHz} \times \text{bit}}{\text{mW} \times \text{mm}^2}$	FOM $\frac{\text{MHz}}{\text{mW}}$
[11]	0.35 μm SiGe	60	1700	32		3000	24	0.76	0.57
[12]	0.35 μm CMOS		2000	8		820	3.99	4.89	2.44
[13]	1 μm bipolar	22	2500	31	1×31	5000	20	0.78	0.5
[14]	0.35 μm SiGe	47	5000	8	8×1	2000	2	10	2.5
[15]	Bipolar InP	137	9200	8	8×1	15000	40	0.12	0.61
[5]	Bipolar InP	300	13000	8	1×8	5420	3.92	4.90	2.4
[16]	Bipolar InP	300	32000	8	4×2	9450	3.92	6.91	3.39
[6]	0.25 μm SiGe	70	6000	9	1×9	308	1	175.32	19.48
[17]	0.09 μm CMOS		1300	24	6×4	350	2	44.6	3.71
[18]	0.35 μm SiGe	200	15000	8	4×2	366	1.16	282.76	40.98
This work (simulated)	0.13 μm SiGe	200	20000	9	$1 + 2 \times 4$	585	1.32	233.02	34.19

Triangular signals provided by the DDS for a phase increment of 1 and the corresponding G/S-PAC output voltages are plotted fig. 8 and fig. 9.

V. CONCLUSION

A novel phase-to-amplitude converter offering gaussian shape capability together with the more classical sinusoidal shape extends low-cost low-power and high-speed DDS panel of waveform. Our G/S-PAC exhibit an optimal simulated SLRR of -43.5dBc in gaussian mode, a SFDR of -44.5dBc in sinus mode, and has allowed the design of an ultra-high-speed 20GHz simulated DDS with a 9-bit frequency resolution, an 8-bit amplitude resolution, on an IBM 0.13 μm BiCMOS SiGe technology.

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